MOS FIELD EFFECT TRANSISTOR 2SK3918

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3918 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, and designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

ORDERING INFORMATION

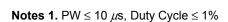
PART NUMBER	PACKAGE		
2SK3918	TO-251 (MP-3)		
2SK3918-ZK	TO-252 (MP-3ZK)		

FEATURES

- Low on-state resistance $R_{DS(on)1} = 7.5 \text{ m}\Omega \text{ MAX.} (V_{GS} = 10 \text{ V}, \text{ ID} = 24 \text{ A})$
- Low Ciss: Ciss = 1300 pF TYP.
- 5 V drive available

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (VGs = 0 V)	VDSS	25	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	D(DC)	±48	А
Drain Current (pulse) Note1	D(pulse)	±192	А
Total Power Dissipation (Tc = 25°C)	P _{T1}	29	W
Total Power Dissipation	P _{T2}	1.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	–55 to +150	°C
Single Avalanche Current Note2	las	22	А
Single Avalanche Energy Note2	Eas	48	mJ



2. Starting T_{ch} = 25°C, V_{DD} = 12.5 V, R_G = 25 Ω , V_{GS} = 20 \rightarrow 0 V

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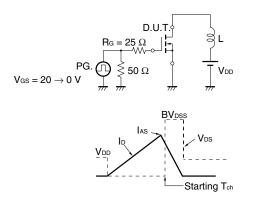
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	Ibss	V _{DS} = 25 V, V _{GS} = 0 V			10	μA
Gate Leakage Current	lgss	V _{GS} = ±20 V, V _{DS} = 0 V			±100	nA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	2.0	2.5	3.0	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = 10 V, I _D = 12 A	6	12		S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = 10 V, I _D = 24 A		5.9	7.5	mΩ
	RDS(on)2	V _{GS} = 5.0 V, I _D = 12 A		11	22.2	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V		1300		pF
Output Capacitance	Coss	V _{GS} = 0 V		310		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		220		pF
Turn-on Delay Time	td(on)	V _{DD} = 12.5 V, I _D = 24 A		13		ns
Rise Time	tr	R _G = 10 Ω		14		ns
Turn-off Delay Time	td(off)			38		ns
Fall Time	tr			14		ns
Total Gate Charge	QG	V _{DD} = 20 V		28		nC
Gate to Source Charge	Q _{GS}	V _{GS} = 10 V		5		nC
Gate to Drain Charge	Qgd	I _D = 48 A		10		nC
Body Diode Forward Voltage Note	VF(S-D)	IF = 48 A, VGS = 0 V		0.98		V
Reverse Recovery Time	trr	IF = 48 A, VGS = 0 V		27		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/ <i>µ</i> s		15		nC

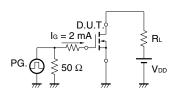
Note Pulsed

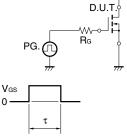
TEST CIRCUIT 1 AVALANCHE CAPABILITY

TEST CIRCUIT 2 SWITCHING TIME

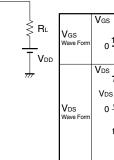


TEST CIRCUIT 3 GATE CHARGE





 $\begin{array}{l} \tau = 1 \; \mu s \\ \text{Duty Cycle} \leq 1\% \end{array}$



VGS Wave Form	$V_{GS} = \frac{10\%}{V_{GS}} = \frac{10\%}{V_{GS}} = \frac{90\%}{V_{GS}}$
VDS Wave Form	$V_{DS} = \underbrace{\begin{array}{c} 10\% \\ V_{DS} \\ 0 \\ t_{d(on)} \\ t_{d($